

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

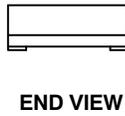
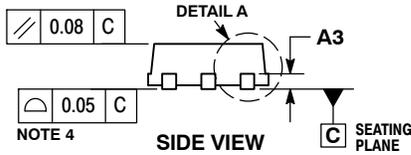
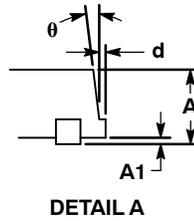
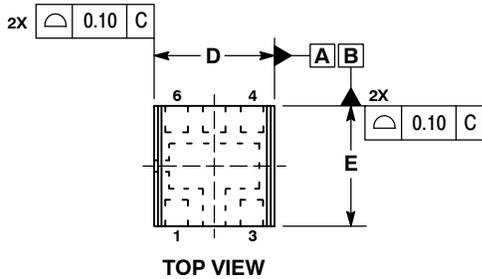
ON Semiconductor®



SCALE 4:1

CUDFN6, 1.6x1.6
CASE 505AE-01
ISSUE B

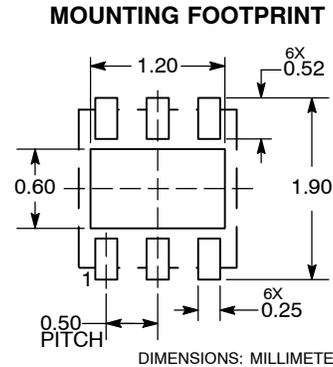
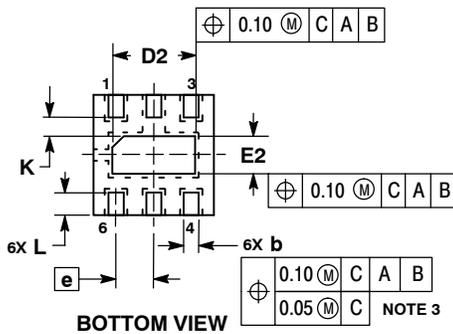
DATE 11 MAY 2010



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.55	0.65
A1	0.00	0.05
A3	0.20 REF	
b	0.15	0.25
D	1.60 BSC	
d	---	0.10
D2	1.00	1.20
E	1.60 BSC	
E2	0.40	0.60
e	0.50 BSC	
K	0.20	---
L	0.25	0.35
θ	4°	10°



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	CUDFN6 1.6X1.6, 0.5P	PAGE 1 OF 2

